

## 20-3300 HIGH TEMPERATURE AND THERMAL SHOCK EPOXY

### DESCRIPTION:

20-3300 is a two part epoxy system formulated to meet the most critical electronic encapsulating requirements. This system has low shrinkage, high tensile and compressive strength.

20-3300 is ideal for high heat and thermal shock exposure. It has excellent adhesion to most substrates and forms a hermetic like seal to protect encapsulated parts. Great choice for high voltage applications.

20-3300 has a convenient 1:1 mix ratio with an extended pot life.

### TYPICAL SPECIFICATIONS:

Mix ratio, by weight	1:1
Mixed viscosity @ 25°C, cps	12,000
Pot life, 100 gram mass @ 25°C	45 Hours
Specific gravity @ 25°C	1.40
Hardness, shore D	87
Tensile strength, psi	7,500
Compressive strength, psi	20,000
Thermal expansion coefficient per °C	$38 \times 10^{-6}$
Operating temperature, °C	-70 to +260
Thermal conductivity, Btu in/ft <sup>2</sup> hr °F	4.0
Dielectric strength, volts/mil	450
Dielectric constant, 60 Hz	4.0
Dissipation factor, 60 Hz	0.01
Volume resistivity, ohm-cm	$3.3 \times 10^{15}$

### INSTRUCTIONS FOR USE:

1. Resin and Catalyst may be heated to 80°C before mixing to reduce the viscosity.
2. By weight, thoroughly mix equal parts 20-3300 Resin and 20-3300 Catalyst. Pot life is 48 hours in a 100gram mass.
3. Pour and cure for 2 hours at 145°C.

### IMPORTANT:

The information in this brochure is based on data obtained by our research and is considered accurate. However, no warranty is expressed or implied regarding the accuracy of these data, the results to be obtained from the use thereof, or that any such use will not infringe any patent. This information is furnished upon the condition that the person receiving it shall make his own tests to determine the suitability thereof for his particular purpose.

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